2SD1734

Silicon PNP Triple-Diffused Planar Type

Horizontal Deflection Output

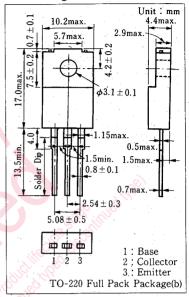
■ Features

- High breakdown voltage, high reliability
- High speed switching
- Wide area of safety operation (ASO)
- "Full Pack" package for simplified mounting on a heat sink with one screw

■ Absolute Maximum Ratings (Tc=25°C)

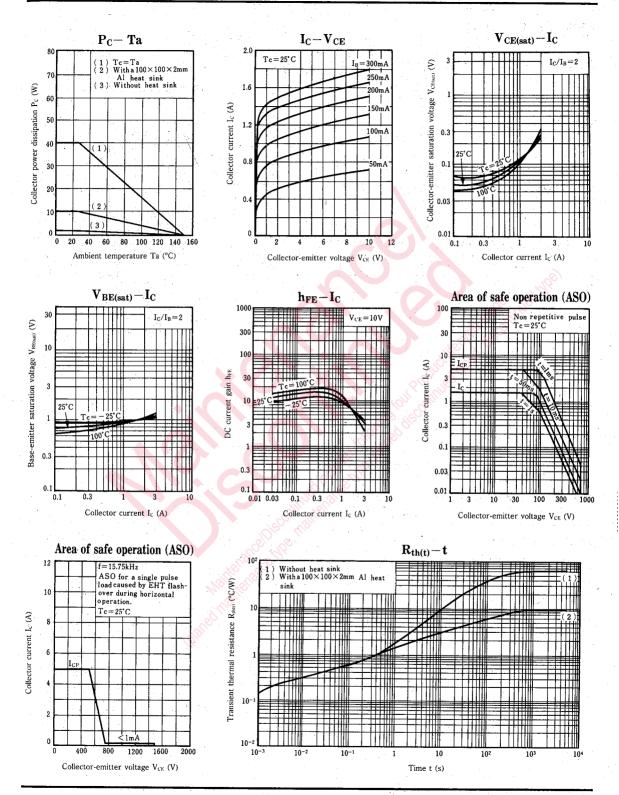
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Item		Symbol	Value	Unit	
Collector-base voltage		V _{CBO}	1500	V	
Collector-emitter voltage		Vces	1500	V	
		V _{CEO}	700	V	
Emitter-base voltage		V _{EBO}	7	V	
Peak collector current		ICP	5	A	
Collector current		Ic	1.5	Α	
Base current		I _B	0.6	Α	
Collector power	Tc=25°C		40	***	
dissipation	Ta=25°C	Pc	2.0	W	
Junction temperature		T_{i}	150	°C	
Storage temperature		Tstg	$-55 \sim +150$	% C 00	

■ Package Dimensions



■ Electrical Characteristics (Tc=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
0.44	I_{CBO}	$V_{CB} = 750 \text{ V}, I_E = 0$			10	μA
Collector cutoff current		$V_{CB} = 1500 \text{ V}, I_E = 0$. 1	mA
Emitter-base voltage	V _{EBO}	$I_E = 500 \text{ mA}, I_C = 0$	7	-		V
DC current gain	hre	$V_{CE} = 5 \text{ V}, I_{C} = 0.5 \text{ A}$	6		30	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 1 A, I_B = 0.4 A$. 8	V
Base-emitter saturation voltage VBE(sat)		$I_C = 1 \text{ A}, I_B = 0.4 \text{ A}$,		1.5	V
Transition frequency	$\sqrt{f_T}$	$V_{CE} = 10V, I_C = 0.5, f = 0.5MHz$		2		MHz
Storage time (L load) t_{sig} $I_C=1$ A, $I_{B1}=0.3$ A				6	μS	
Fall time (L load) t_f $I_{B2} = -0.3 \text{ A}, L_B = 5 \mu\text{H}$				0.8	. μS	
Storage time (R load)	tstg	$I_C = 1 \text{ A}, I_{B1} = 0.3 \text{ A}$		1 -		μS
Fall time (R load)	t _f	$I_{B2} = -0.6 \text{ A}, \ V_{CC} = 200 \text{ V}$		0.2		μS



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